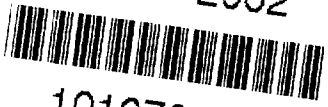


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Form PTO-1595 (Rev. 03/01) OMB No. 0651-0027 (exp. 5/31/2002) REC

U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office

ATTORNEY DOCKET: 740819-740

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying parties: Satoshi TAMURA Masahiro OGAWA Masahiro ISHIDA Masaaki YURI

2. Name and address of receiving party(ies) Name: Matsushita Electric Industrial Co., Ltd. Internal Address: 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501, Japan

01/25/02

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance: [X] Assignment [] Merger [] Security Agreement [] Change of Name [] Other

Street Address: City: State: Zip:

Additional name(s) & address(es) attached? Yes No

Execution Date: January 21, 2002

4. Application number(s) or patent number(s); If this document is being filed together with a new application, the execution date of the application is: January 21, 2002 A. Patent Application No.(s) B. Patent No.(s) Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed: Name: Eric J. Robinson Internal Address: Nixon Peabody LLP Street Address: 8180 Greensboro Drive, Suite 800 City: McLean State: VA Zip: 22102

6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41)\$40.00 [X] Enclosed [] Authorized to be charged to deposit account 8. Deposit account number: 19-2380 (Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Eric J. Robinson Name of Person Signing Signature Date January 25, 2002

Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231

Vertical stamp: JCS57 U.S. PTO 10/054844 01/25/02

Handwritten notes and stamps: 01/23/2002 SDIRETAL 00000021 10054844 40.00 DP

PATENT REEL: 012523 FRAME: 0730

Attorney Docket No. _____

ASSIGNMENTWHEREAS, **Satoshi TAMURA, Masahiro OGAWA, Masahiro ISHIDA, and Masaaki****YURI**

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in **MANUFACTURING METHOD OF COMPOUND SEMICONDUCTOR WAFER** for which the undersigned has (have):

- (a) filed an application for Letters Patent of the United States of America on _____ having Serial No. _____; or
- (b) executed an application for Letters Patent of the United States of America on the date(s) indicated below; and

WHEREAS, **Matsushita Electric Industrial Co., Ltd.**

of

1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501, Japan

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto the Assignee the full and exclusive right to the said invention in the United States of America and its territories and for all foreign countries, dependencies and possessions and the entire right, title and interest in and to the application and any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to the Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

This Assignment has been executed by the undersigned on the date(s) indicated.

Date: January 21, 2002, *Satoshi Tamura*
Satoshi TAMURA

Date: January 21, 2002, *Masahiro Ogawa*
Masahiro OGAWA

Date: January 21, 2002, *Masahiro Ishida*
Masahiro ISHIDA

Date: January 21, 2002, *Masaaki Yuri*
Masaaki YURI

Date: _____, _____

Date: _____, _____

Date: _____, _____

Date: _____, _____